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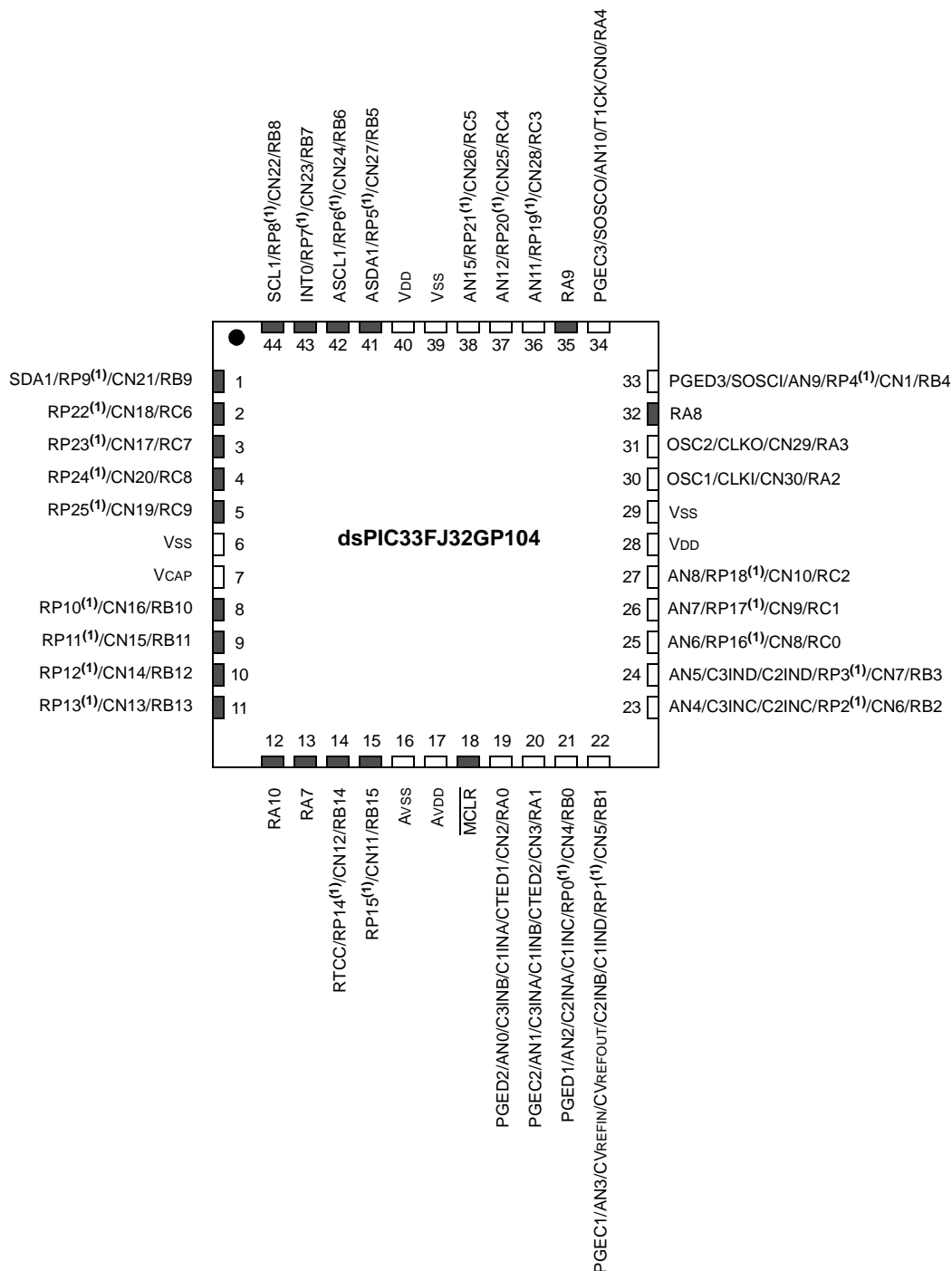
Details

Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPS
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32gp101-e-p

Pin Diagrams (Continued)

44-Pin QFN⁽²⁾

■ = Pins are up to 5V tolerant



- Note 1:** The RPN pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.
- Note 2:** The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

TABLE 4-33: PORTB REGISTER MAP FOR dsPIC33FJ32GP101 DEVICES

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	02C8	TRISB<15:14>		—	—	—	—	TRISB<9:7>		—	—	TRISB4		—	—	TRISB<1:0>		C393
PORTB	02CA	RB<15:14>		—	—	—	—	RB<9:7>		—	—	RB4		—	—	RB<1:0>		xxxx
LATB	02CC	LATB<15:14>		—	—	—	—	LATB<9:7>		—	—	LATB4		—	—	LATB<1:0>		xxxx
ODCB	02CE	ODCB<15:14>		—	—	—	—	ODCB<9:7>		—	—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-34: PORTB REGISTER MAP FOR dsPIC33FJ32MC101 DEVICES

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	02C8	TRISB<15:12>				—	—	TRISB<9:7>			—	—	TRISB4	—	—	TRISB<1:0>		F393
PORTB	02CA	RB<15:12>				—	—	RB<9:7>			—	—	RB4	—	—	RB<1:0>		xxxx
LATB	02CC	LATB<15:12>				—	—	LATB<9:7>			—	—	LATB4	—	—	LATB<1:0>		xxxx
ODCB	02CE	ODCB<15:12>				—	—	ODCB<9:7>			—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-35: PORTB REGISTER MAP FOR dsPIC33FJ32(GP/MC)102 AND dsPIC33FJ32(GP/MC)104 DEVICES

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	02C8	TRISB<15:0>																FFFF
PORTB	02CA	RB<15:0>																xxxx
LATB	02CC	LATB<15:0>																xxxx
ODCB	02CE	ODCB<15:5>											—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-36: PORTC REGISTER MAP FOR dsPIC33FJ32(GP/MC)104 DEVICES

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISC	02D0	—	—	—	—	—	—	TRISC<9:0>										FFFF
PORTC	02D2	—	—	—	—	—	—	RC<9:0>										xxxx
LATC	02D4	—	—	—	—	—	—	LATC<9:0>										xxxx
ODCC	02D6	—	—	—	—	—	—	ODCC<9:6>				—	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

dsPIC33FJ16(GP/MC)101/102 AND dsPIC33FJ32(GP/MC)101/102/104

REGISTER 5-1: NVMCON: FLASH MEMORY CONTROL REGISTER

R/SO-0 ⁽¹⁾	R/W-0 ⁽¹⁾	R/W-0 ⁽¹⁾	U-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0 ⁽¹⁾	U-0	U-0	R/W-0 ⁽¹⁾	R/W-0 ⁽¹⁾	R/W-0 ⁽¹⁾	R/W-0 ⁽¹⁾
—	ERASE	—	—	NVMOP3 ⁽²⁾	NVMOP2 ⁽²⁾	NVMOP1 ⁽²⁾	NVMOP0 ⁽²⁾
bit 7							bit 0

Legend:	SO = Settable Only bit
R = Readable bit	W = Writable bit
-n = Value at POR	'1' = Bit is set
	U = Unimplemented bit, read as '0'
	'0' = Bit is cleared
	x = Bit is unknown

- bit 15 **WR:** Write Control bit⁽¹⁾
1 = Initiates a Flash memory program or erase operation; the operation is self-timed and the bit is cleared by hardware once operation is complete
0 = Program or erase operation is complete and inactive
- bit 14 **WREN:** Write Enable bit⁽¹⁾
1 = Enables Flash program/erase operations
0 = Inhibits Flash program/erase operations
- bit 13 **WRERR:** Write Sequence Error Flag bit⁽¹⁾
1 = An improper program or erase sequence attempt or termination has occurred (bit is set automatically on any set attempt of the WR bit)
0 = The program or erase operation completed normally
- bit 12-7 **Unimplemented:** Read as '0'
- bit 6 **ERASE:** Erase/Program Enable bit⁽¹⁾
1 = Performs the erase operation specified by NVMOP<3:0> on the next WR command
0 = Performs the program operation specified by NVMOP<3:0> on the next WR command
- bit 5-4 **Unimplemented:** Read as '0'
- bit 3-0 **NVMOP<3:0>:** NVM Operation Selection bits^(1,2)
If ERASE = 1:
1111 = No operation
1101 = Erase General Segment
1100 = No operation
0011 = No operation
0010 = Memory page erase operation
0001 = No operation
0000 = No operation
If ERASE = 0:
1111 = No operation
1101 = No operation
1100 = No operation
0011 = Memory word program operation
0010 = No operation
0001 = No operation
0000 = No operation

Note 1: These bits can only be reset on a POR.

2: All other combinations of NVMOP<3:0> are unimplemented.

REGISTER 5-2: NVMKEY: NONVOLATILE MEMORY KEY REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—

8.3 Clock Switching Operation

Applications are free to switch among any of the four clock sources (Primary, LP, FRC and LPRC) under software control at any time. To limit the possible side effects of this flexibility, dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices have a safeguard lock built into the switch process.

Note: Primary Oscillator mode has three different submodes (MS, HS and EC), which are determined by the POSCMD<1:0> Configuration bits. While an application can switch to and from Primary Oscillator mode in software, it cannot switch among the different primary submodes without reprogramming the device.

8.3.1 ENABLING CLOCK SWITCHING

To enable clock switching, the FCKSM1 Configuration bit in the FOSC Configuration register must be programmed to '0'. (Refer to **Section 23.1 "Configuration Bits"** for further details.) If the FCKSM1 Configuration bit is unprogrammed ('1'), the clock switching function and Fail-Safe Clock Monitor function are disabled. This is the default setting.

The NOSCx control bits (OSCCON<10:8>) do not control the clock selection when clock switching is disabled. However, the COSCx bits (OSCCON<14:12>) reflect the clock source selected by the FNOSCx Configuration bits.

The OSWEN control bit (OSCCON<0>) has no effect when clock switching is disabled; it is held at '0' at all times.

8.3.2 OSCILLATOR SWITCHING SEQUENCE

Performing a clock switch requires this basic sequence:

1. If desired, read the COSC bits (OSCCON<14:12>) to determine the current oscillator source.
2. Perform the unlock sequence to allow a write to the OSCCON register high byte.
3. Write the appropriate value to the NOSCx control bits (OSCCON<10:8>) for the new oscillator source.
4. Perform the unlock sequence to allow a write to the OSCCON register low byte.
5. Set the OSWEN bit (OSCCON<0>) to initiate the oscillator switch.

Once the basic sequence is completed, the system clock hardware responds automatically as follows:

1. The clock switching hardware compares the COSCx status bits with the new value of the NOSCx control bits. If they are the same, the clock switch is a redundant operation. In this case, the OSWEN bit is cleared automatically and the clock switch is aborted.
2. If a valid clock switch has been initiated, the LOCK and CF (OSCCON<5,3>) status bits are cleared.
3. The new oscillator is turned on by the hardware if it is not currently running. If a crystal oscillator must be turned on, the hardware waits until the Oscillator Start-up Timer (OST) expires. If the new source is using the PLL, the hardware waits until a PLL lock is detected (LOCK = 1).
4. The hardware waits for 10 clock cycles from the new clock source and then performs the clock switch.
5. The hardware clears the OSWEN bit to indicate a successful clock transition. In addition, the NOSCx bit values are transferred to the COSCx status bits.
6. The old clock source is turned off at this time, with the exception of LPRC (if WDT or FSCM is enabled) or LP (if LPOSCEN remains set).

Note 1: The processor continues to execute code throughout the clock switching sequence. Timing-sensitive code should not be executed during this time.

2: Direct clock switches between any Primary Oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

3: Refer to **"Oscillator (Part VI)"** (DS70644) in the *"dsPIC33/PIC24 Family Reference Manual"* for details.

8.4 Fail-Safe Clock Monitor (FSCM)

The Fail-Safe Clock Monitor (FSCM) allows the device to continue to operate even in the event of an oscillator failure. The FSCM function is enabled by programming. If the FSCM function is enabled, the LPRC internal oscillator runs at all times (except during Sleep mode) and is not subject to control by the Watchdog Timer.

In the event of an oscillator failure, the FSCM generates a clock failure trap event and switches the system clock over to the FRC oscillator. Then, the application program can either attempt to restart the oscillator or execute a controlled shutdown. The trap can be treated as a Warm Reset by simply loading the Reset address into the oscillator fail trap vector.

If the PLL multiplier is used to scale the system clock, the internal FRC is also multiplied by the same factor on clock failure. Essentially, the device switches to FRC with PLL on a clock failure.

9.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**Watchdog Timer and Power-Saving Modes**” (DS70196) in the “dsPIC33/PIC24 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. Devices can manage power consumption in four different ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

9.1 Clock Frequency and Clock Switching

dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC<2:0> bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 8.0 “Oscillator Configuration”**.

9.2 Instruction-Based Power-Saving Modes

dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 9-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to wake-up.

9.2.1 SLEEP MODE

The following occurs in Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current
- The Fail-Safe Clock Monitor does not operate, since the system clock source is disabled
- The LPRC clock continues to run in Sleep mode if the WDT is enabled
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode
- Some device features or peripherals may continue to operate. This includes items such as the Input Change Notification (ICN) on the I/O ports or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled

The device will wake-up from Sleep mode on any of the these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 9-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV #SLEEP_MODE    ; Put the device into SLEEP mode
PWRSAV #IDLE_MODE      ; Put the device into IDLE mode
```

9.5 PMD Control Registers

REGISTER 9-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0
T5MD ⁽¹⁾	T4MD ⁽¹⁾	T3MD	T2MD	T1MD	—	PWM1MD	—
bit 15						bit 8	

R/W-0	U-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0
I2C1MD	—	U1MD	—	SPI1MD	—	—	AD1MD ⁽²⁾
bit 7						bit 0	

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15 **T5MD:** Timer5 Module Disable bit⁽¹⁾
 1 = Timer5 module is disabled
 0 = Timer5 module is enabled
- bit 14 **T4MD:** Timer4 Module Disable bit⁽¹⁾
 1 = Timer4 module is disabled
 0 = Timer4 module is enabled
- bit 13 **T3MD:** Timer3 Module Disable bit
 1 = Timer3 module is disabled
 0 = Timer3 module is enabled
- bit 12 **T2MD:** Timer2 Module Disable bit
 1 = Timer2 module is disabled
 0 = Timer2 module is enabled
- bit 11 **T1MD:** Timer1 Module Disable bit
 1 = Timer1 module is disabled
 0 = Timer1 module is enabled
- bit 10 **Unimplemented:** Read as '0'
- bit 9 **PWM1MD:** PWM1 Module Disable bit
 1 = PWM1 module is disabled
 0 = PWM1 module is enabled
- bit 8 **Unimplemented:** Read as '0'
- bit 7 **I2C1MD:** I2C1 Module Disable bit
 1 = I2C1 module is disabled
 0 = I2C1 module is enabled
- bit 6 **Unimplemented:** Read as '0'
- bit 5 **U1MD:** UART1 Module Disable bit
 1 = UART1 module is disabled
 0 = UART1 module is enabled
- bit 4 **Unimplemented:** Read as '0'

Note 1: These bits are available in dsPIC33FJ32(GP/MC)10X devices only.

2: PCFGx bits have no effect if the ADC module is disabled by setting this bit. When the bit is set, all port pins that have been multiplexed with ANx will be in Digital mode.

FIGURE 12-2: TIMER2 AND TIMER4 (16-BIT) BLOCK DIAGRAM⁽¹⁾

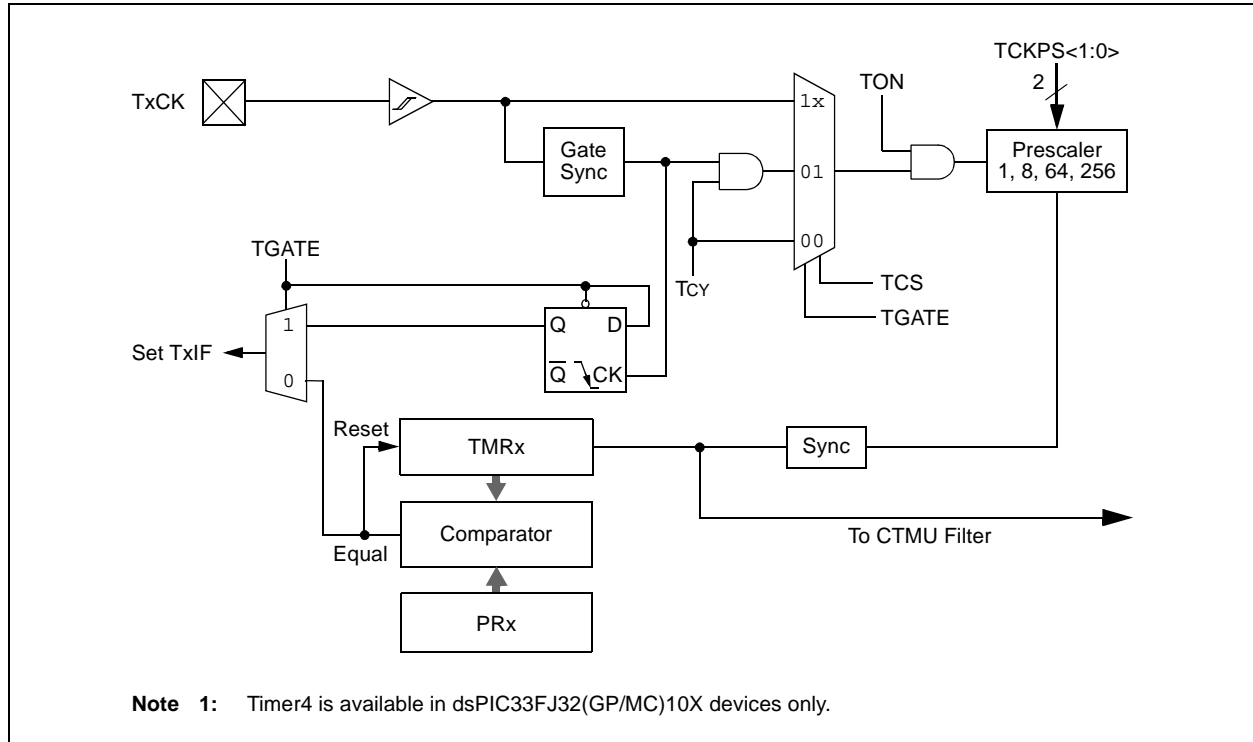
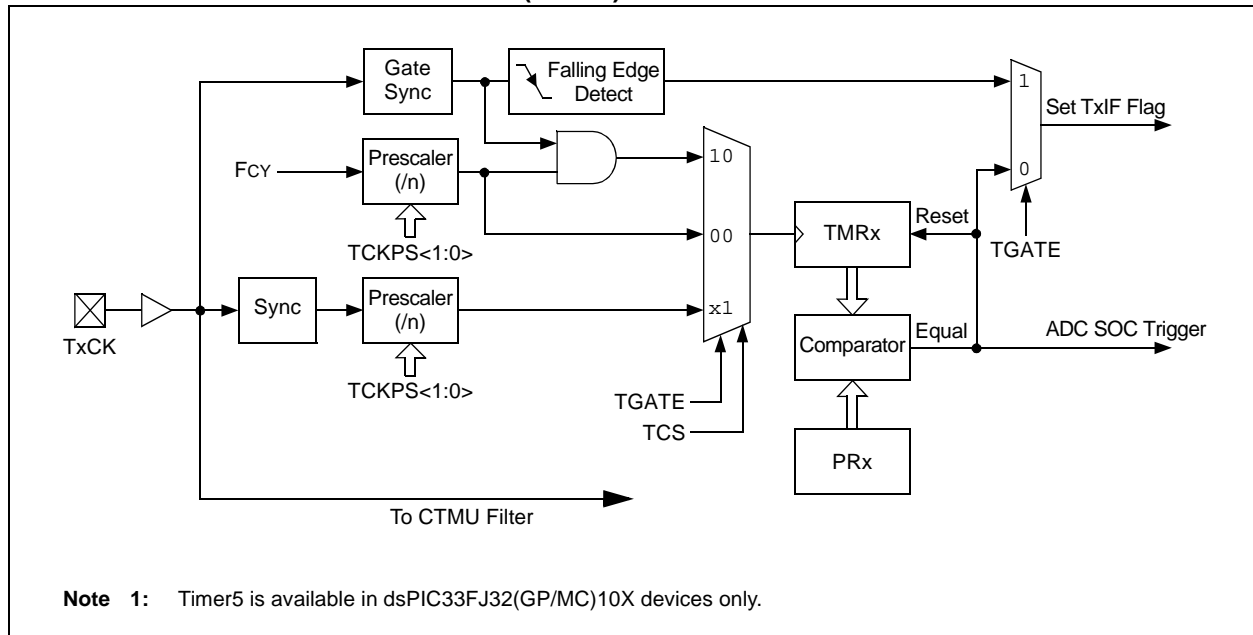


FIGURE 12-3: TIMER3 AND TIMER5 (16-BIT) BLOCK DIAGRAM⁽¹⁾



13.0 INPUT CAPTURE

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**Input Capture**” (DS70198) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The input capture module is useful in applications requiring frequency (period) and pulse measurement. The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices support up to three input capture channels.

The input capture module captures the 16-bit value of the selected Time Base register when an event occurs on the ICx pin. The events that cause a capture event are listed below in three categories:

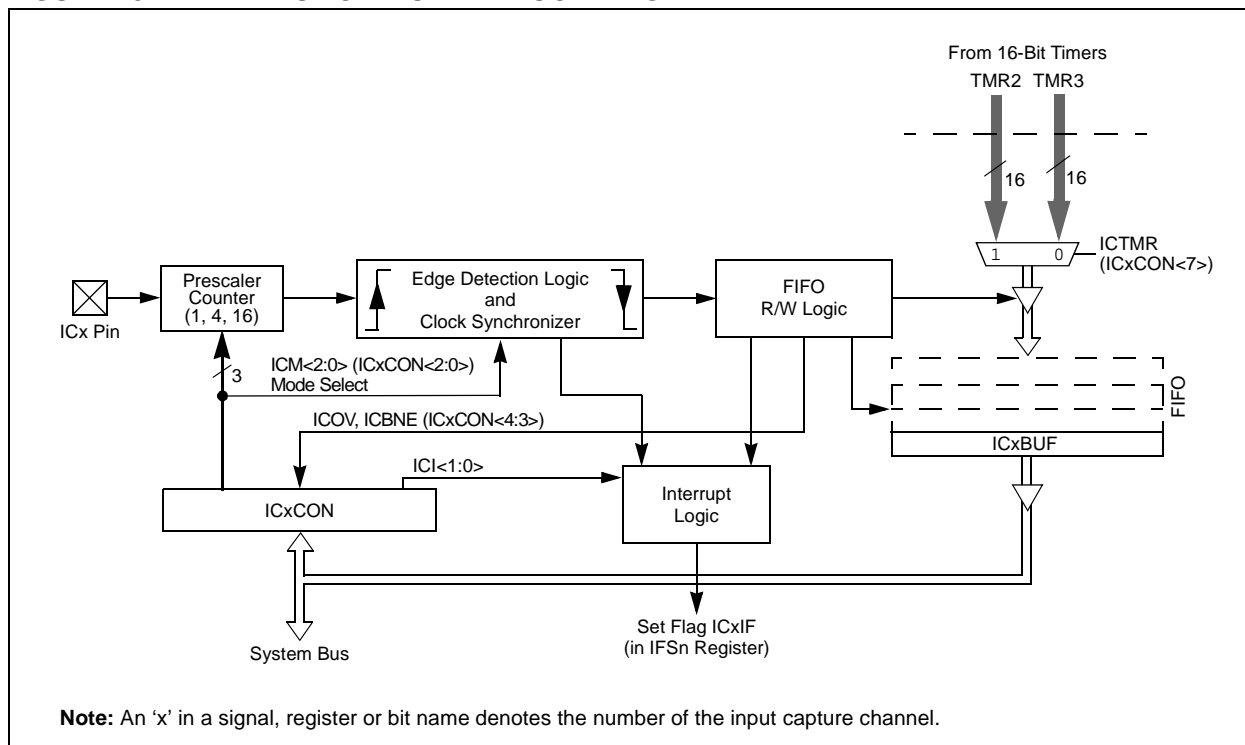
- Simple Capture Event modes:
 - Capture timer value on every falling edge of input at ICx pin
 - Capture timer value on every rising edge of input at ICx pin
- Capture timer value on every edge (rising and falling).
- Prescaler Capture Event modes:
 - Capture timer value on every 4th rising edge of input at ICx pin
 - Capture timer value on every 16th rising edge of input at ICx pin

Each input capture channel can select one of two 16-bit timers (Timer2 or Timer3) for the time base. The selected timer can use either an internal or external clock.

Other operational features include:

- Device wake-up from capture pin during CPU Sleep and Idle modes
- Interrupt on input capture event
- 4-word FIFO buffer for capture values:
 - Interrupt optionally generated after 1, 2, 3 or 4 buffer locations are filled
- Use of input capture to provide additional sources of external interrupts

FIGURE 13-1: INPUT CAPTURE x BLOCK DIAGRAM



REGISTER 15-4: PxSECMP: PWMx SPECIAL EVENT COMPARE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTDIR ⁽¹⁾	SEVTCMP<14:8> ⁽²⁾						
bit 15	bit 8						

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTCMP<7:0> ⁽²⁾							
bit 7	bit 0						

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15 **SEVTDIR:** Special Event Trigger Time Base Direction bit⁽¹⁾

1 = A Special Event Trigger will occur when the PWMx time base is counting down

0 = A Special Event Trigger will occur when the PWMx time base is counting up

bit 14-0 **SEVTCMP<14:0>:** Special Event Compare Value bits⁽²⁾

Note 1: SEVTDIR is compared with PTDIR (PxTMR<15>) to generate the Special Event Trigger.

2: PxSECMP<14:0> is compared with PxTMR<14:0> to generate the Special Event Trigger.

16.1 SPI Helpful Tips

1. In Frame mode, if there is a possibility that the master may not be initialized before the slave:
 - a) If FRMPOL (SPIxCON2<13>) = 1, use a pull-down resistor on \overline{SSx} .
 - b) If FRMPOL = 0, use a pull-up resistor on \overline{SSx} .

Note: This insures that the first frame transmission after initialization is not shifted or corrupted.

2. In Non-Framed 3-Wire mode (i.e., not using \overline{SSx} from a master):
 - a) If CKP (SPIxCON1<6>) = 1, always place a pull-up resistor on \overline{SSx} .
 - b) If CKP = 0, always place a pull-down resistor on \overline{SSx} .

Note: This will insure that during power-up and initialization, the master/slave will not lose sync due to an errant SCK transition that would cause the slave to accumulate data shift errors for both transmit and receive, appearing as corrupted data.

3. FRMEN (SPIxCON2<15>) = 1 and SSEN (SPIxCON1<7>) = 1 are exclusive and invalid. In Frame mode, SCKx is continuous and the Frame Sync pulse is active on the \overline{SSx} pin, which indicates the start of a data frame.

Note: Not all third-party devices support Frame mode timing. Refer to the SPI electrical characteristics for details.

4. In Master mode only, set the SMP bit (SPIxCON1<9>) to a '1' for the fastest SPI data rate possible. The SMP bit can only be set at the same time or after the MSTEN bit (SPIxCON1<5>) is set.
5. To avoid invalid slave read data to the master, the user's master software must ensure enough time for slave software to fill its write buffer before the user application initiates a master write/read cycle. It is always advisable to pre-load the SPIxBUF Transmit register in advance of the next master transaction cycle. SPIxBUF is transferred to the SPIx Shift register and is empty once the data transmission begins.
6. The SPI related pins (SDI1, SDO1, SCK1) are located at fixed positions in the dsPIC33FJ16(GP/MC)10X devices. The same pins are remappable in the dsPIC33FJ32(GP/MC)10X devices.

16.2 SPI Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en554109>

16.2.1 KEY RESOURCES

- “Serial Peripheral Interface (SPI)” (DS70206) in the “dsPIC33/PIC24 Family Reference Manual”.
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related “dsPIC33/PIC24 Family Reference Manual” sections
- Development Tools

REGISTER 17-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	AMSK<9:8>	
bit 15						bit 8	

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
AMSK<7:0>							
bit 7						bit 0	

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-10

Unimplemented: Read as '0'

bit 9-0

AMSK<9:0>: Mask for Address Bit x Select bits

1 = Enables masking for Bit x of incoming message address; bit match not required in this position

0 = Disables masking for Bit x; bit match required in this position

TABLE 24-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
9	BTG	BTG f, #bit4	Bit Toggle f	1	1	None
		BTG ws, #bit4	Bit Toggle ws	1	1	None
10	BTSC	BTSC f, #bit4	Bit Test f, Skip if Clear	1	1 (2 or 3)	None
		BTSC ws, #bit4	Bit Test ws, Skip if Clear	1	1 (2 or 3)	None
11	BTSS	BTSS f, #bit4	Bit Test f, Skip if Set	1	1 (2 or 3)	None
		BTSS ws, #bit4	Bit Test ws, Skip if Set	1	1 (2 or 3)	None
12	BTST	BTST f, #bit4	Bit Test f	1	1	Z
		BTST.C ws, #bit4	Bit Test ws to C	1	1	C
		BTST.Z ws, #bit4	Bit Test ws to Z	1	1	Z
		BTST.C ws, Wb	Bit Test ws<Wb> to C	1	1	C
		BTST.Z ws, Wb	Bit Test ws<Wb> to Z	1	1	Z
13	BTSTS	BTSTS f, #bit4	Bit Test then Set f	1	1	Z
		BTSTS.C ws, #bit4	Bit Test ws to C, then Set	1	1	C
		BTSTS.Z ws, #bit4	Bit Test ws to Z, then Set	1	1	Z
14	CALL	CALL lit23	Call subroutine	2	2	None
		CALL Wn	Call indirect subroutine	1	2	None
15	CLR	CLR f	f = 0x0000	1	1	None
		CLR WREG	WREG = 0x0000	1	1	None
		CLR ws	ws = 0x0000	1	1	None
		CLR Acc, Wx, Wxd, Wy, Wyd, AWB	Clear Accumulator	1	1	OA, OB, SA, SB
16	CLRWDT	CLRWDT	Clear Watchdog Timer	1	1	WDTO, Sleep
17	COM	COM f	f = \bar{f}	1	1	N, Z
		COM f, WREG	WREG = \bar{f}	1	1	N, Z
		COM ws, Wd	Wd = \bar{ws}	1	1	N, Z
18	CP	CP f	Compare f with WREG	1	1	C, DC, N, OV, Z
		CP Wb, #lit5	Compare Wb with lit5	1	1	C, DC, N, OV, Z
		CP Wb, ws	Compare Wb with ws (Wb – ws)	1	1	C, DC, N, OV, Z
19	CP0	CP0 f	Compare f with 0x0000	1	1	C, DC, N, OV, Z
		CP0 ws	Compare ws with 0x0000	1	1	C, DC, N, OV, Z
20	CPB	CPB f	Compare f with WREG, with Borrow	1	1	C, DC, N, OV, Z
		CPB Wb, #lit5	Compare Wb with lit5, with Borrow	1	1	C, DC, N, OV, Z
		CPB Wb, ws	Compare Wb with ws, with Borrow (Wb – ws – C)	1	1	C, DC, N, OV, Z
21	CPSEQ	CPSEQ Wb, Wn	Compare Wb with Wn, skip if =	1	1 (2 or 3)	None
22	CPSGT	CPSGT Wb, Wn	Compare Wb with Wn, skip if >	1	1 (2 or 3)	None
23	CPSLT	CPSLT Wb, Wn	Compare Wb with Wn, skip if <	1	1 (2 or 3)	None
24	CPSNE	CPSNE Wb, Wn	Compare Wb with Wn, skip if ≠	1	1 (2 or 3)	None
25	DAW	DAW Wn	Wn = decimal adjust Wn	1	1	C
26	DEC	DEC f	f = f – 1	1	1	C, DC, N, OV, Z
		DEC f, WREG	WREG = f – 1	1	1	C, DC, N, OV, Z
		DEC ws, Wd	Wd = ws – 1	1	1	C, DC, N, OV, Z
27	DEC2	DEC2 f	f = f – 2	1	1	C, DC, N, OV, Z
		DEC2 f, WREG	WREG = f – 2	1	1	C, DC, N, OV, Z
		DEC2 ws, Wd	Wd = ws – 2	1	1	C, DC, N, OV, Z
28	DISI	DISI #lit14	Disable Interrupts for k instruction cycles	1	1	None

FIGURE 26-2: EXTERNAL CLOCK TIMING

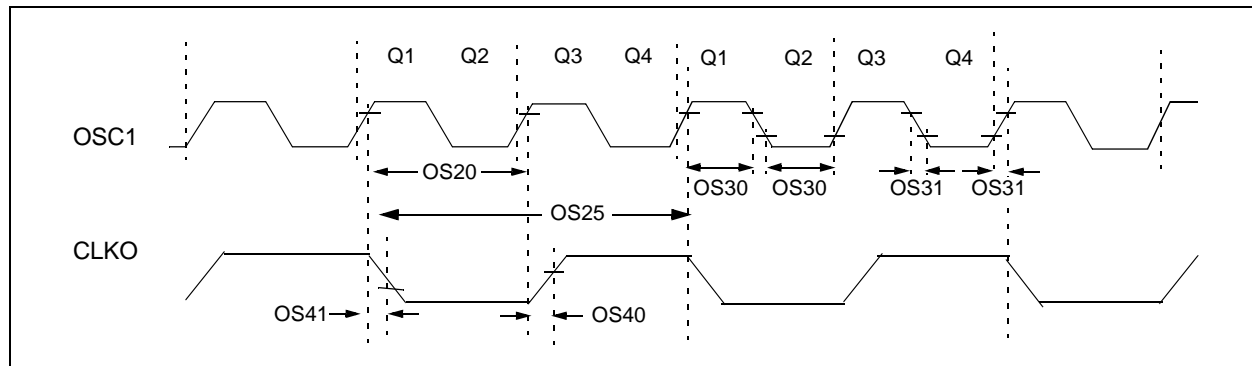


TABLE 26-16: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symb	Characteristic	Min	Typ ⁽¹⁾	Max	Units	Conditions
OS10	FIN	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC	—	32	MHz	EC
		Oscillator Crystal Frequency	3.0	—	10	MHz	MS
			10	—	32	MHz	HS
			31	—	33	kHz	SOSC
OS20	Tosc	Tosc = 1/Fosc	31.25	—	DC	ns	
OS25	Tcy	Instruction Cycle Time ^(2,4)	62.5	—	DC	ns	
OS30	TosL, TosH	External Clock in (OSC1) ⁽⁵⁾ High or Low Time	0.45 x Tosc	—	—	ns	EC
OS31	TosR, TosF	External Clock in (OSC1) ⁽⁵⁾ Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time ^(3,5)	—	6	10	ns	
OS41	TckF	CLKO Fall Time ^(3,5)	—	6	10	ns	
OS42	GM	External Oscillator Transconductance ⁽⁴⁾	14	16	18	mA/V	VDD = 3.3V, TA = +25°C

Note 1: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

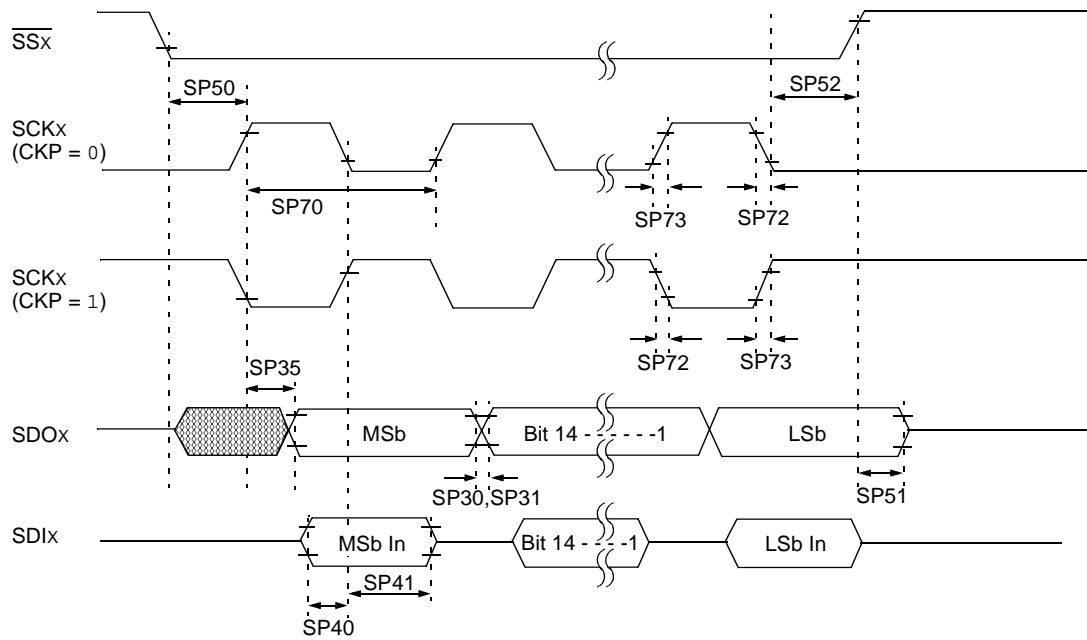
2: Instruction cycle period (Tcy) equals two times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type, under standard operating conditions, with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin. When an external clock input is used, the “max.” cycle time limit is “DC” (no clock) for all devices.

3: Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.

4: These parameters are characterized by similarity, but are tested in manufacturing at FIN = 32 MHz only.

5: These parameters are characterized by similarity, but are not tested in manufacturing.

FIGURE 26-18: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ16(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-43: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS FOR dsPIC33FJ32(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Typ ⁽²⁾	Max	Units	Conditions
SP70	TscP	Maximum SCKx Input Frequency	—	—	15	MHz	See Note 3
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and Note 4
SP73	TscR	SCKx Input Rise Time	—	—	—w	ns	See Parameter DO31 and Note 4
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and Note 4
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and Note 4
SP35	Tsch2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx} \downarrow$ to SCKx \uparrow or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx} \uparrow$ to SDOx Output High-Impedance	10	—	50	ns	See Note 4
SP52	Tsch2ssH TscL2ssH	\overline{SSx} after SCKx Edge	1.5 TCY + 40	—	—	ns	See Note 4

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCKx clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

27.0 HIGH-TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 26.0 “Electrical Characteristics”** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes: High temperature. For example, Parameter DC10 in **Section 26.0 “Electrical Characteristics”** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 high-temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings⁽¹⁾

Ambient temperature under bias ⁽³⁾	-40°C to +150°C
Storage temperature	-65°C to +160°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to VSS ⁽⁴⁾	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD < 3.0V ⁽⁴⁾	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V ⁽⁴⁾	-0.3V to 5.6V
Maximum current out of VSS pin	300 mA
Maximum current into VDD pin ⁽²⁾	250 mA
Maximum junction temperature	+155°C
Maximum current sourced/sunk by any 4x I/O pin	4 mA
Maximum current sourced/sunk by any 8x I/O pin	8 mA
Maximum current sunk by all ports combined	80 mA
Maximum current sourced by all ports combined ⁽²⁾	80 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” can cause permanent damage to the device. This is a stress rating only and functional operation of the device at those, or any other conditions above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 27-2).

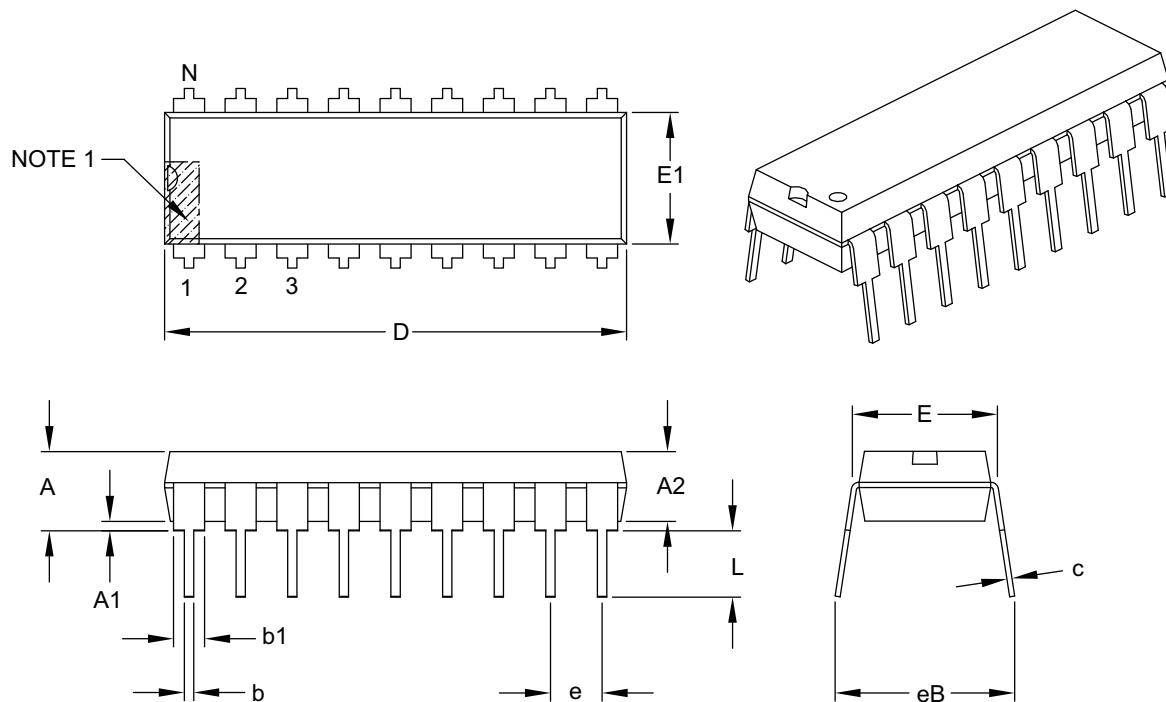
3: AEC-Q100 reliability testing for devices intended to operate at +150°C is 1,000 hours. Any design in which the total operating time from +125°C to +150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

4: Refer to the “Pin Diagrams” section for 5V tolerant pins.

28.2 Package Details

18-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES		
		MIN	NOM	MAX
Number of Pins	N	18		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.880	.900	.920
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.014
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M.

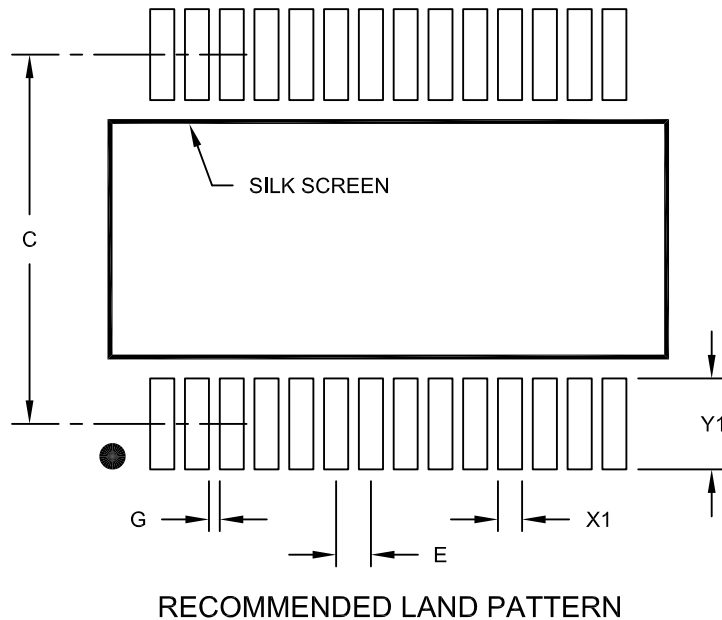
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-007B

dsPIC33FJ16(GP/MC)101/102 AND dsPIC33FJ32(GP/MC)101/102/104

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

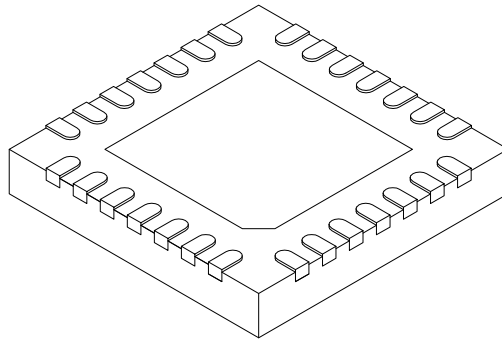
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN] With 0.55 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension	Units Limits	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.20 REF		
Overall Width	E	6.00 BSC		
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D	6.00 BSC		
Exposed Pad Length	D2	3.65	3.70	4.20
Terminal Width	b	0.23	0.30	0.35
Terminal Length	L	0.50	0.55	0.70
Terminal-to-Exposed Pad	K	0.20	-	-

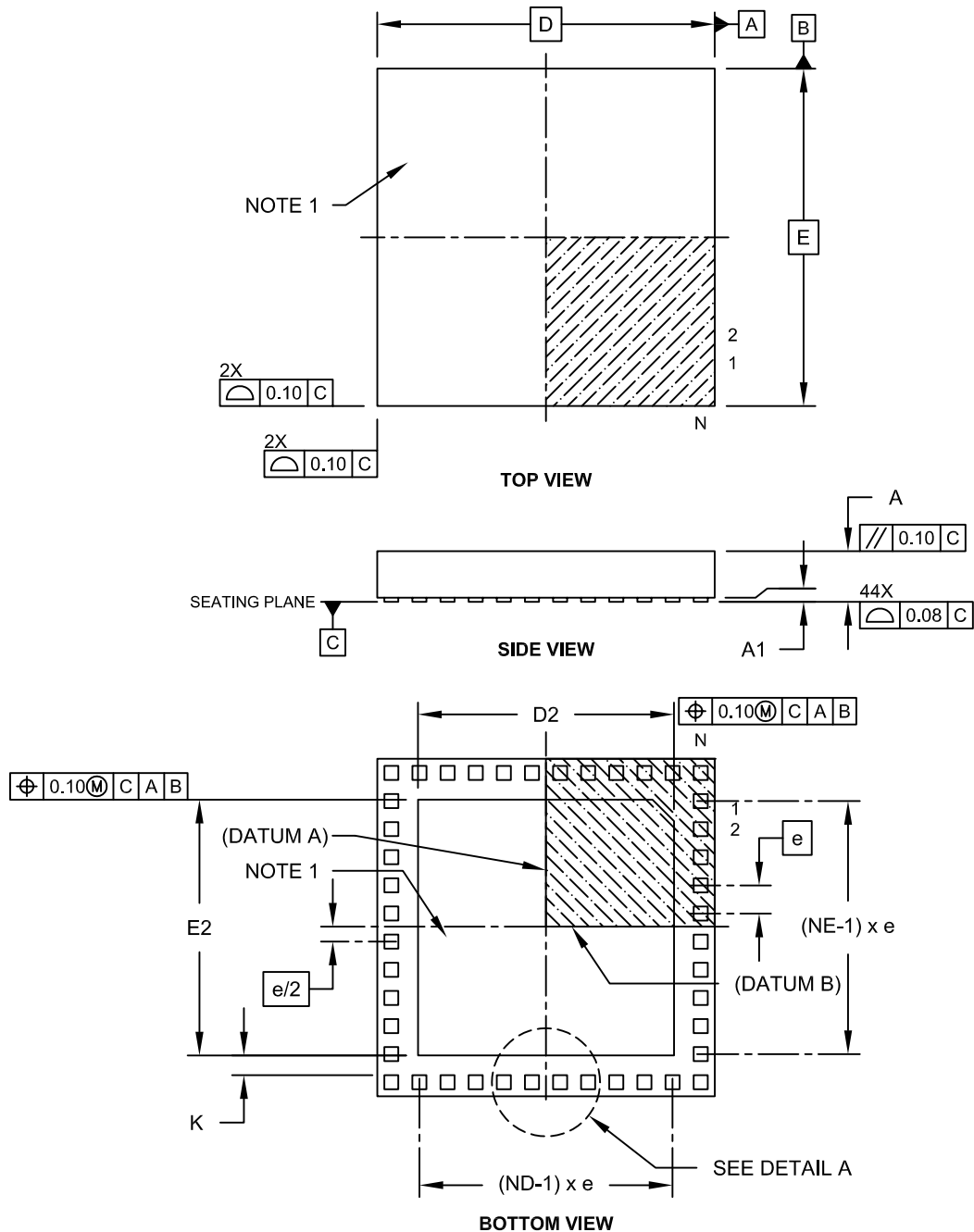
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105C Sheet 2 of 2

**44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body
With Exposed Pad [VTLA]**

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-157C Sheet 1 of 2